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NEWS RELEASE

VSP™ Electro-Deposited Copper Foil for High-Frequency Circuit Boards Production Capacity Enhanced

— Approx. 6 billion yen being invested to increase capacity of Taiwan and Malaysia Plants to 1,200 tons per month —

Mitsui Kinzoku Company, Limited (NOU Takeshi, President; hereinafter “Mitsui Kinzoku”) announces that it will increase its Taiwan (Taiwan Copper Foil Co., Ltd.) and Malaysia Plants’ (Mitsui Copper Foil (Malaysia) Sdn Bhd) copper foil for high-frequency circuit board VSP™ production capacity by 360 tons per month, to a total of 1,200 tons per month by September 2028, investing approximately 6 billion yen in these two plants currently manufacturing this copper foil. This is in addition to the plan to increase capacity to 840 tons per month by September 2026 that was announced in the VSP™ Electro-Deposited Copper Foil for High-Frequency Circuit Boards Production Capacity Additionally Enhanced news release dated August 20, 2025.

Mitsui Kinzoku’s VSP™ copper foil for high-frequency circuit boards has been used in servers, routers, switches and other high-performance communication infrastructure devices, since it greatly aids the reduction of transmission loss in printed circuit boards at high frequency signal bands. Currently, Mitsui Kinzoku is shifting HVLP5-graded products to the mass production phase for applications relating to AI infrastructure, and these products are increasingly used by big tech companies. The demand for Mitsui Kinzoku’s VSP™ is rapidly growing, and it is expected to increase furthermore.

In this environment, production capacity will be increased in stages. Specifically, it will be increased to 1,000 tons per month by September 2027 and to 1,200 tons per month by September 2028. Additionally, about 6 billion yen will be invested to expand and divert existing equipment currently using for general-purpose copper foil, improve productivity with existing equipment and newly install surface treatment machine at the Taiwan Plant (Taiwan Copper Foil Co., Ltd.) and the Malaysia Plant (Mitsui Copper Foil (Malaysia) Sdn Bhd), in addition to the previously announced increase of production capacity to 840 tons per month by September 2026. As planned, this investment fully satisfies Mitsui Kinzoku’s investment criteria in the copper foil business. Mitsui Kinzoku is promoting ROIC management.

These steps will result in an increase of Mitsui Kinzoku’s total production capacity. Mitsui Kinzoku will continue its efforts to additionally increase production capacity to meet the continued growth of demand in the future.

Mitsui Kinzoku will contribute to the realization of a sustainable society by implementing its vision for 2030, “Building new businesses — and the future — with our material intelligence,” based on its purpose, “We promote the well-being of the world through a spirit of exploration and diverse technologies.”

■ VSP™ production capacity (for reference)

Unit: tons/month	As of November 2025	March 2026	September 2026	September 2027	September 2028
Taiwan Plant	560	600	720	760	860
Malaysia Plant	60	120	120	240	340
Total	620	720	840	1,000	1,200

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General-purpose copper foil



VSP™

Photo: A reflection of an apple mango in a copper foil surface

* VSP™ is characterized by its outstanding surface smoothness comparable to that of a mirror.



Taiwan Plant

(Taiwan Copper Foil Co., Ltd. (“TCF”))



Malaysia Plant

(Mitsui Copper Foil (Malaysia) Sdn Bhd)

Photo: The Taiwan and Malaysia Plants, where the increase in production capacity is planned

(Reference)

Main functions of VSP™:

It is a copper foil for high-frequency circuit boards for communication infrastructure devices, including servers, switches, routers and base stations.